



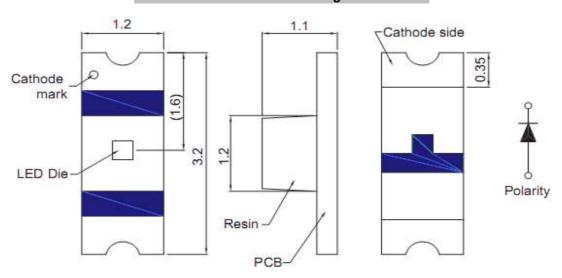




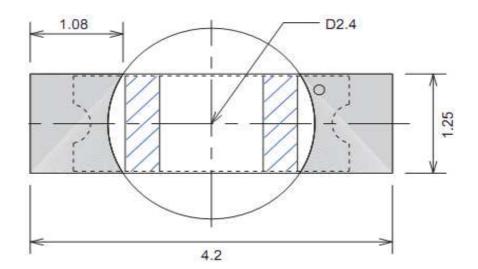
Applications

- Interior automotive lighting
 - Optical indicators
- Communication Products
 - Backlighting
 - Toys

Technical Drawing



Recommended Soldering Pattern



Notes:

All dimensions in mm tolerance is ± 0.1 mm unless otherwise noted.

SMT Top View LED Yellow

Part No.: **M11B9002**

DRW:	Wang	CHKD	Wung	MATL:	Chui	DATE	03.12.2009
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Absolute Maximum Ratings

Ta=25°C

Item	Symbol	GaAsP	Unit
Power Dissipation	P_{D}	65	mW
DC Forward Current	I _F	25	mA
Plused Forward Current	I _{FP} *	100	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T _{OP}	-30 to 80	°C
Storage Temperature	T _{ST}	-40 to 85	°C

^{* 0.1} msec pulse, 10% duty cycle

Electrcal / Optical Characteristics

I_F=20mA Ta=25°C

Ermitting Color		Yellow	
Material		GaAsP	
Forward Voltage	typ.	2.1	V_{F}
I of ward voitage	max.	2.6	V_{F}
Wavelength	λD	590	nm
_	λP	589	nm
typ.	Δλ	35	nm
Color Temperature	min.		K
Color remperature	max.		K
Luminous Intensity *	min.	3.6	mcd
Lummous intensity	typ.	9	mcd
Reverse Current	max.		μA
Viewing Angle	201/2	140	

^{*} Per NIST standards

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email: info@edcon-components.com

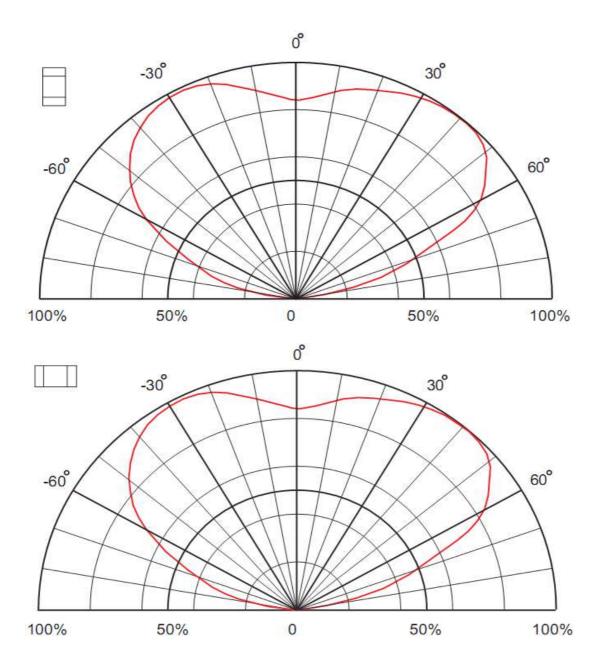








Directive Characteristics



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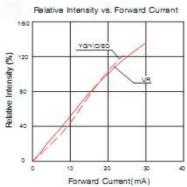


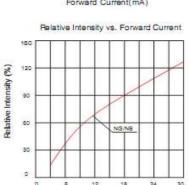




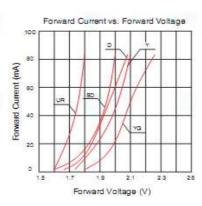


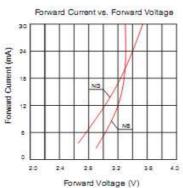
Curvs

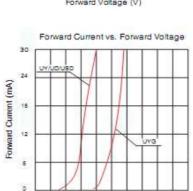




Forward Current(mA)



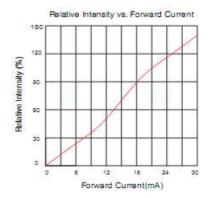


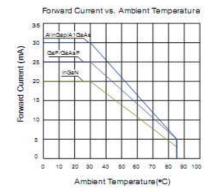


Forward Voltage (V)

2.3

1.5





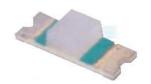
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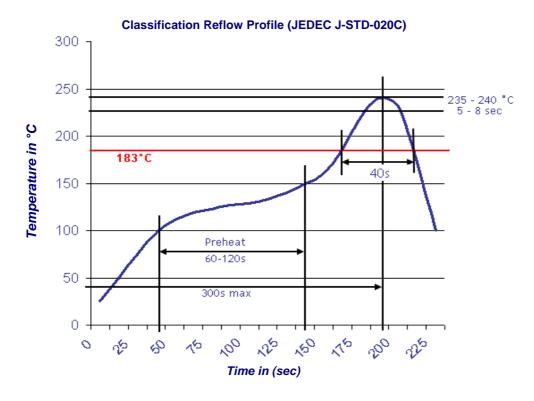






Solder Condition

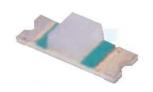
Lead Free Solder



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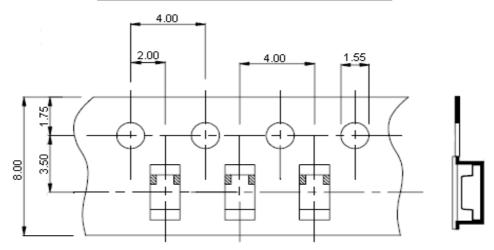




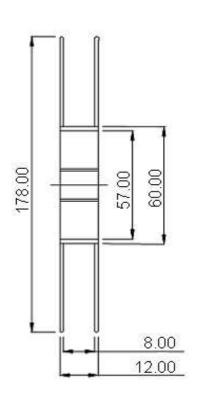


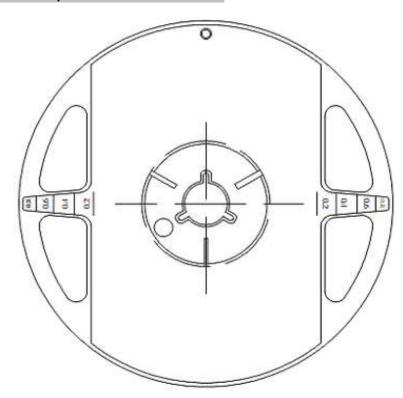


Packing Specifications



Reel Specifications

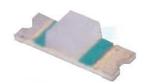




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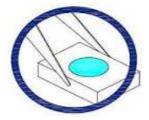




Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although ist characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might leads to damage and premature failure of th LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools



2. Do not directly touch or handle the silicone lens surfance. It may damage the internal circuitry.





3. Do not stack together assembled PCBs containing exposed LEDs. Outside impact may scratch the silicone lens or damage the internal circuitry.



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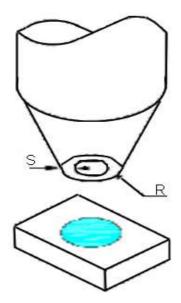








- 4. The outer diameter of the TOP LED pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
- 5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



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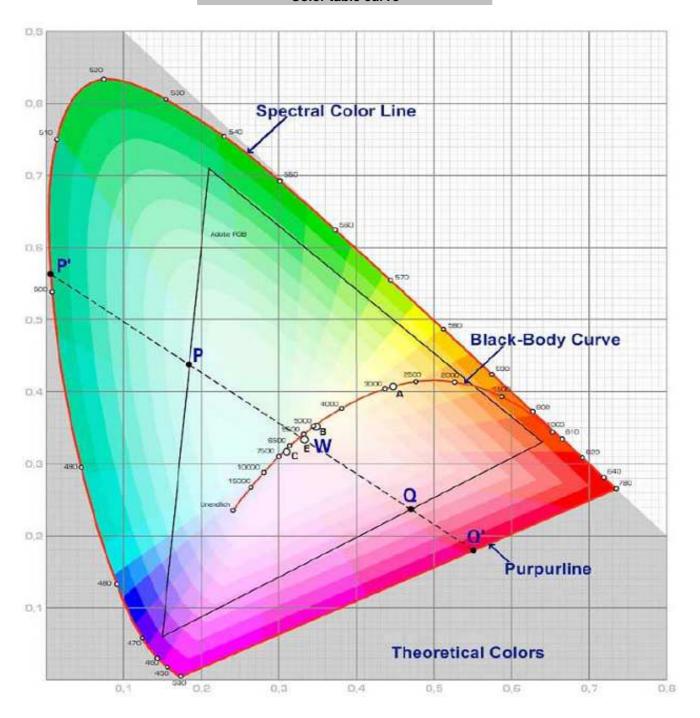








Color table curve



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